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# ***NoAmpTPC: read-out of a TPC without gaseous amplification***

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# The NoAmpTPC read-out project

## Interest of direct read-out of ionization electrons

- Better energy resolution if very low noise level
- Less constraints on choice of the gas mixture
- Simplified read-out → robust TPC
- No ion production
- Large segmentation of the read-out → good spatial resolution
- Could be interesting for several TPC project
- ATTRACT application in 2019 but failed...

## Principle of the read-out

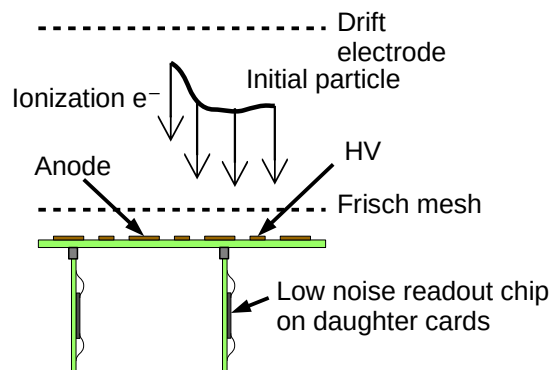
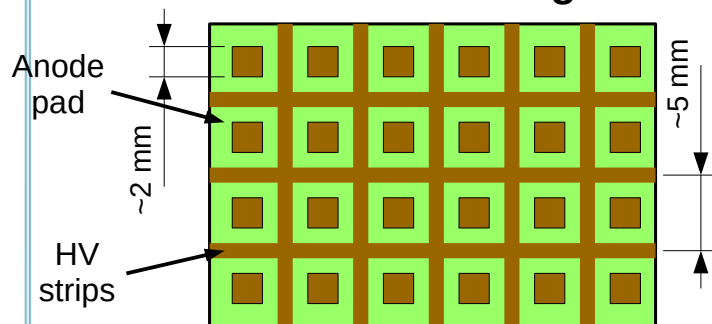
- Read-out board with large segmentation and very low-noise electronics
- Small read-out pads with Frish grid + focusing by polarized strips
- Very low-noise front-end chips → IDeF-X LXE (100 e<sup>-</sup> with 10 pF capacitance) mounted on board or on daughter cards on the back side
- Electronics chain based on Dream chip



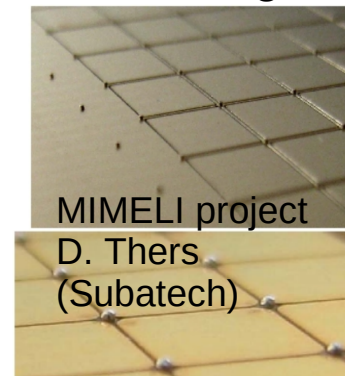
2800 μm

IDeF-X HD LXe chip  
32 channels  
33e<sup>-</sup> + 6e<sup>-</sup>/pF noise  
with 12μs peaking time

### Possible design



### Other designs

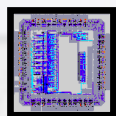


# IDeF-X ASIC family

Very low noise chips for solid detectors, to be considered for ionization detection

AMS 0.35 $\mu$ m

IDeF-X : spectrometry channel



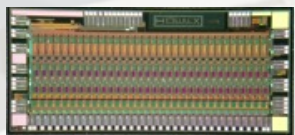
**V0**, Chip test, CSAs



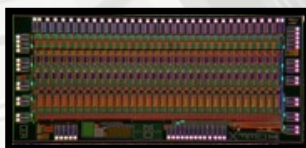
**V1.0** Full analog chains



**V1.1** Analog + Mux / Caliste64  
System approach  
Radiation evaluation



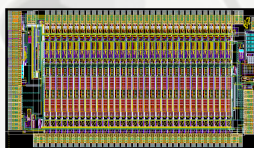
**V.2 – ECLAIRs** / Caliste 256  
Fully programmable  
Space qualified



**BD – SSL/CINEMA**  
Fully programmable  
Si or DSSD adapted

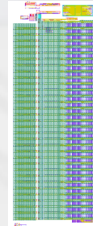


**HD – Caliste HD**  
Low Power  
Fully programmable  
HD-BD upcoming



**HD-LXE–**  
Low Power  
Fully programmable  
// outputs

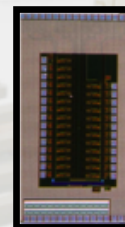
ADC



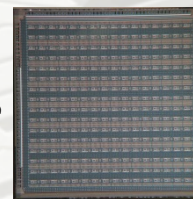
**OWB-1 – ADC** //  
32 channel  
13 bits  
Low power  
SEL hardened

XFAB 0.18 $\mu$ m

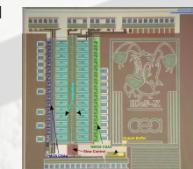
IDeF-X : spectrometry channel



**Caterpylar**  
Chip test  
Very low noise  
Very low power



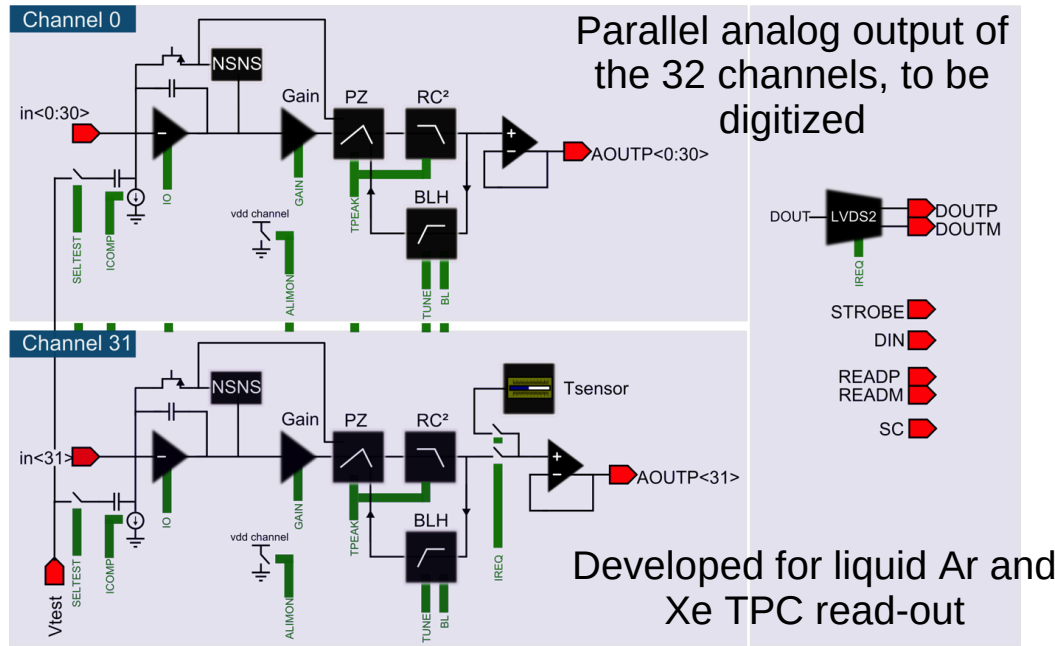
**D<sup>2</sup>R<sub>1</sub>**, 256 Pixels  
300 $\times$ 300  $\mu$ m<sup>2</sup>  
Auto-trigger  
very low power.



**Caterpylar AMS**  
Chip test  
Very low noise  
Very low power

AMS 0.18 $\mu$ m

# IDeF-X HD LXE version



- 32 channels. Parallel analog output
- CSA (new concept)
- Gain (50, 100, 150, 200mV/fC)
- PZ cancellation
- RC<sup>2</sup> filter ( $T_{PEAK}=1$  to 10 $\mu$ s)
- Base Line Holder (switchable)

- Embedded temperature Sensor with absolute resolution of 0.5°C.
- Slow Control
  - ✓ Multi ASIC interface
  - ✓ Gain
  - ✓  $T_{PEAK}$
  - ✓  $I_{CSA}$  (23-100 $\mu$ A)
  - ✓  $I_{LEAK}$
  - ✓ Channel mask
  - ✓ Test mask
  - ✓ AlimON
- Power on reset
- “smart” LVDS input/output
- Hardened digital standard cell
- Low power: 0.8mW /channel

# IDeF-X HD (LXE) performance

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cea

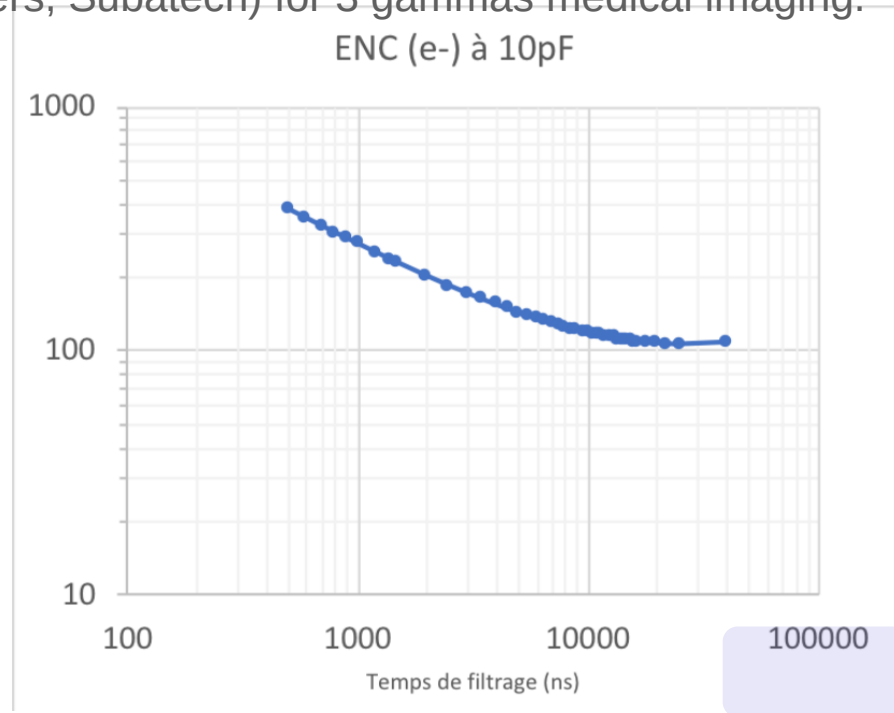
saclay



6400  $\mu\text{m}$

2800  $\mu\text{m}$

LXE version used for XEMIS project (liquid Xenon TPC, D.Thers, Subatech) for 3 gammas medical imaging.



Noise levels :

- $80 e^- + 15 e^-/\text{pF}$  with  $1 \mu\text{s}$  peaking time
- $33 e^- + 6 e^-/\text{pF}$  with  $12 \mu\text{s}$  peaking time

# Dream electronics chain

## Constraints

IDeF-X chips only do amplification and shaping

Triggering, sampling, digitization and recording to be done by other electronics + DAQ

Need to record signal amplitude, time, optionally signal shape

## Possible electronics chain

Several front-end chips can be considered:

- AGET and DREAM (IRFU + others): 64 channels, auto-triggable, analog sampling on SCA capacitor array (512 samples 1 to 50MHz), to be combined with ADC, front-end stages can be by-passed
- SAMPA (ALICE TPC): 32 channels, integrated ADC (10 bits 10-20 MS/s) and DSP, triggerless continuous read-out mode, 10 x 320Mb/s data links
- VMM (ATLAS NSW): 64 channels, auto-triggable, peak and time measurements, integrated ADC (10 bits), triggerless mode
- Other solutions ?

## Choice for NoAmpTPC proto

DREAM "FEU" (front-end unit) card with 8 chips → 512 channels

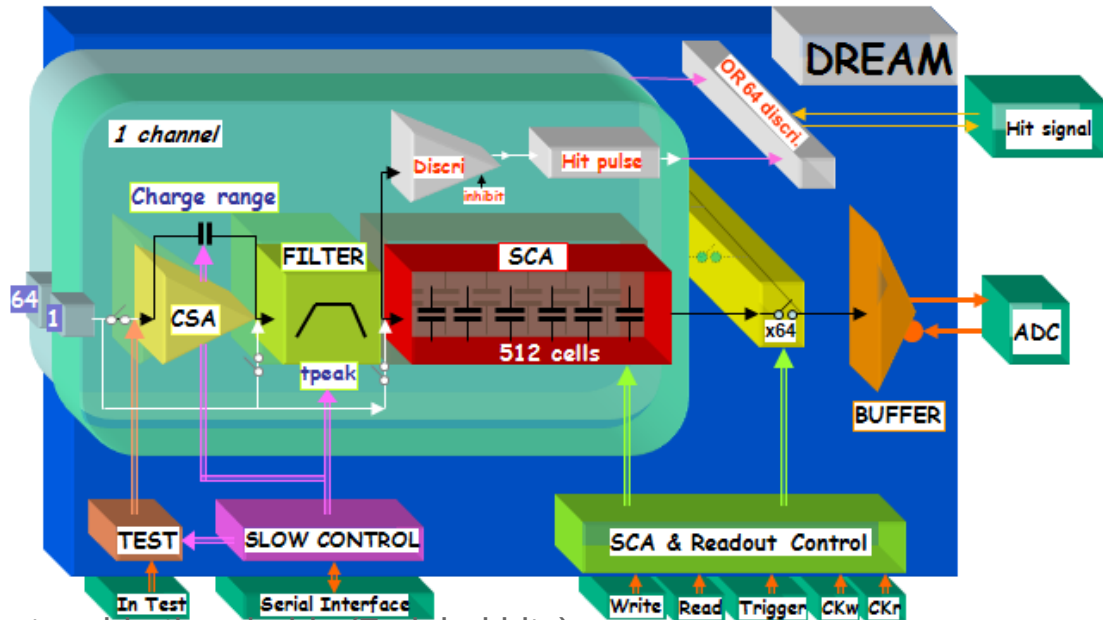
ADC chips integrated to the card

Standalone DAQ



# DREAM front-end chip

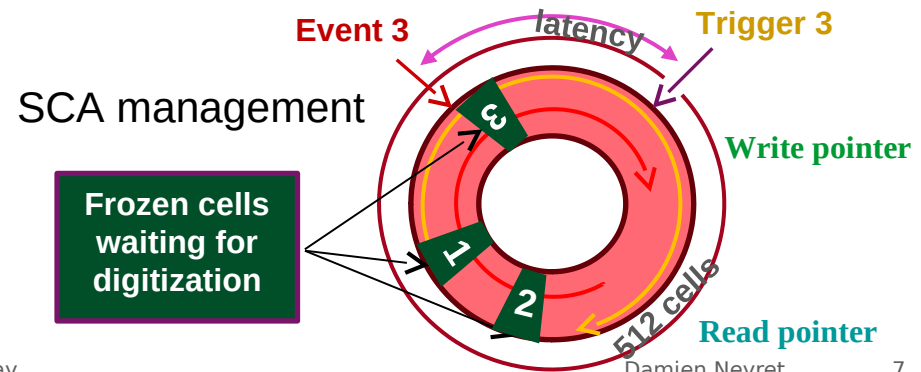
- 64 channels
- 4 gains / channel: 50 fC, 100 fC, 200 fC, 600fC
- 16 peaking times: 50 ns to 1  $\mu$ s
- 512(511) analog memory cells
- Sampling rates: 1MHz to 50 MHz
- Read-out rate: 20 MHz



- Auto trigger: discriminator + tunable thresholds (7 global bits)
- Multiplicity information: digital signal (LVDS); 8 multiplicity levels
- SCA read-out: only "triggered" cells of the 64 channels
- Possibility to short the CSA and input directly into RC2 filter or into SCA

## DREAM ASIC

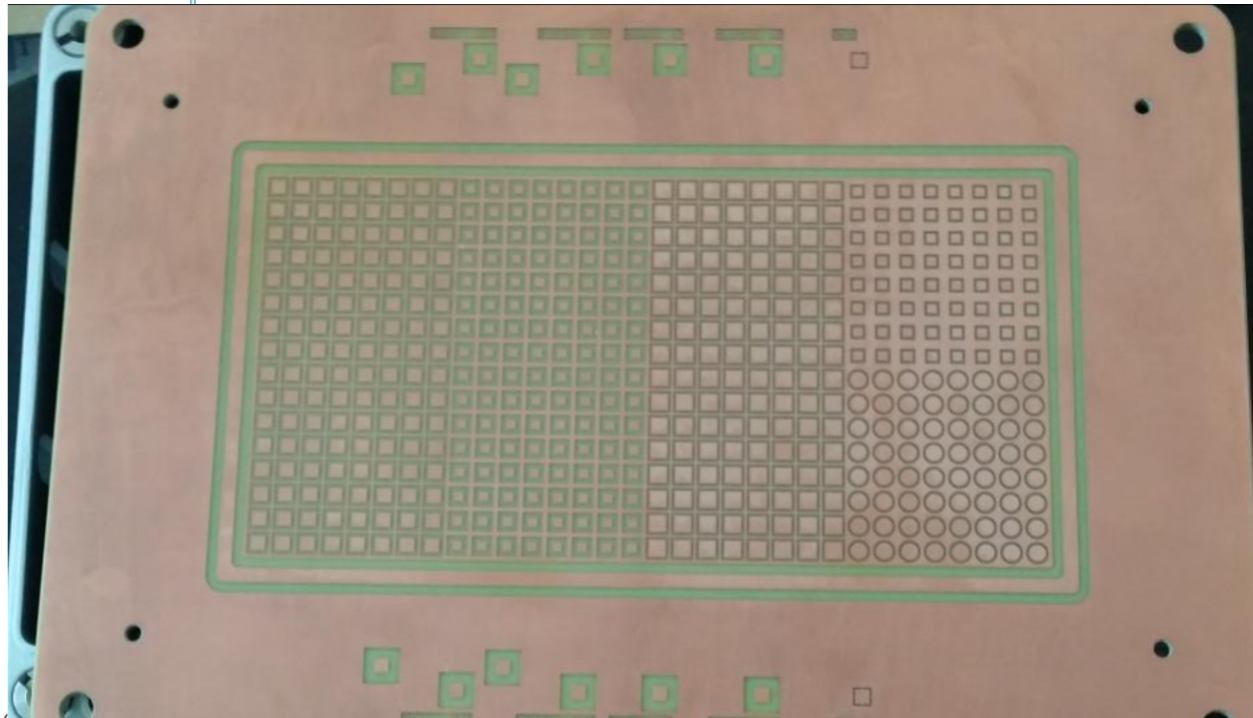
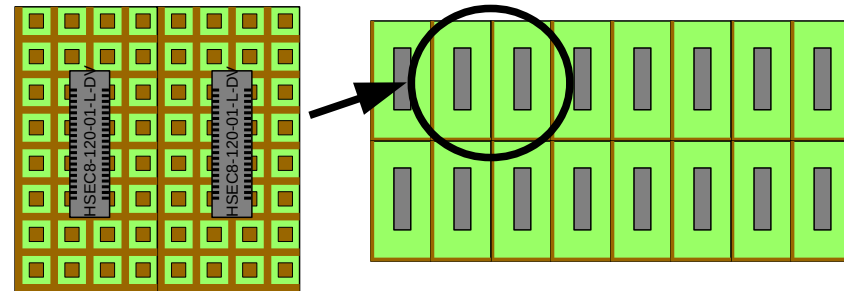
- developed for CLAS12 Micromegas
- stand high input capacity (> 200pF)
- large trigger and counting rates



# NoAmpTPC prototype design

## Read-out board

- 512 pads within 8x16cm active area
- 5mm pitch, several pad sizes
- HV guard strips to focus electrons on pads
- Pad geometry optimization using Garfield++ simulation
- Produced in FR4 material, production with low  $\epsilon_R$  material failed up to now
- Integration in progress





# Prototype design at Saclay

## IDeF-X daughter cards

Holding the IDeF-X chip

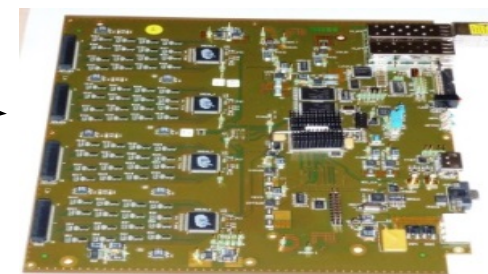
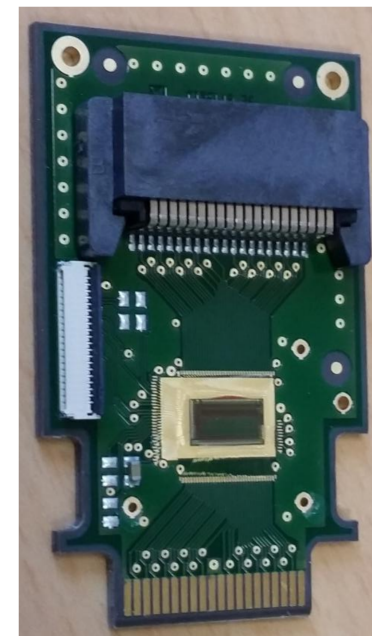
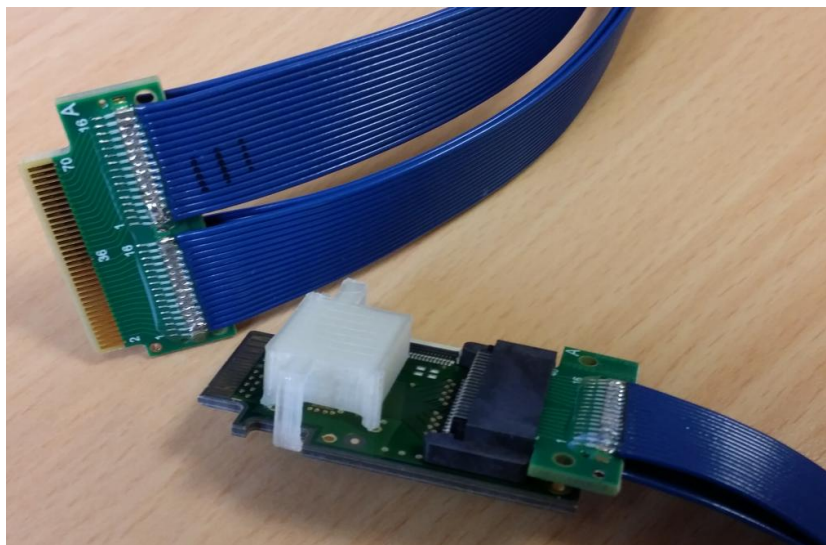
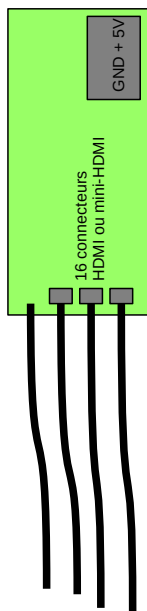
Samtec HSEC8 connectors

Powered and controlled by an external service card

Connected to DREAM FEU card by micro-coax flat cables

20 cards produced with low  $\epsilon_R$  material (RO5880)

Power/control service card still in production



# Garfield simulation of the read-out plane

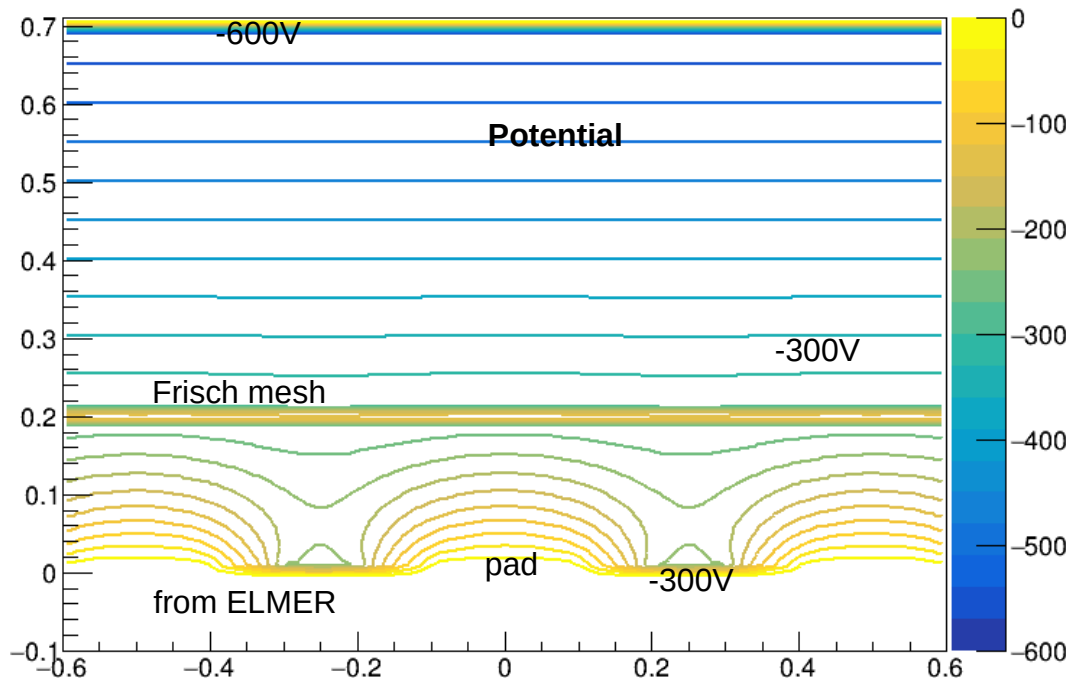
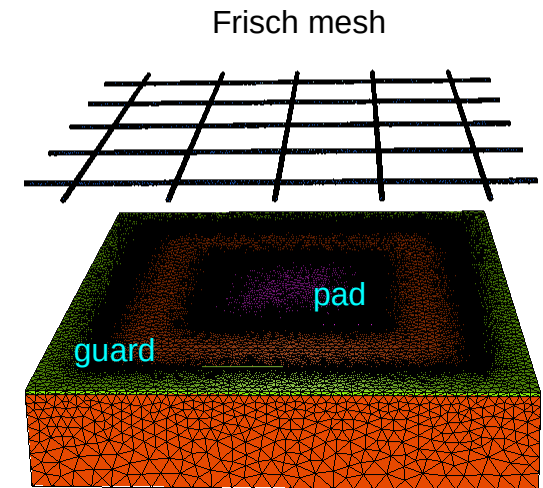
## Simulated design

- Read-out plane with electrode pads and focusing HV guard strips
- Amplitude of signal, electrons lost on Frisch mesh and on FR4
- Goal: optimization of pads/focusing guard strips geometry, evolution vs electrodes HV
- Method: GMSH (geometry, 2D/3D meshing) + ELMER (electric field) + Garfield++ (electron and ion drift), Ar+5% isobutane gas mixture 1 bar



drift

from GMSH



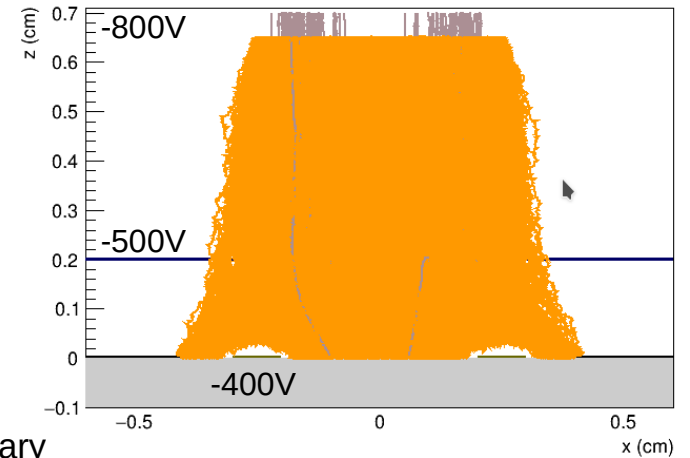
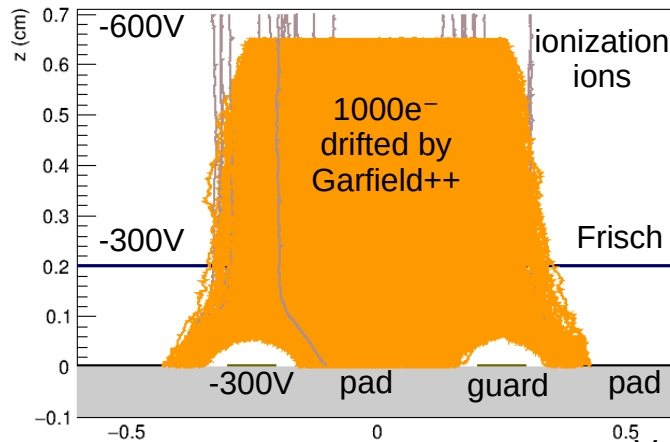
# Garfield++ simulation of the read-out plane

## Dependence to the electrode voltage

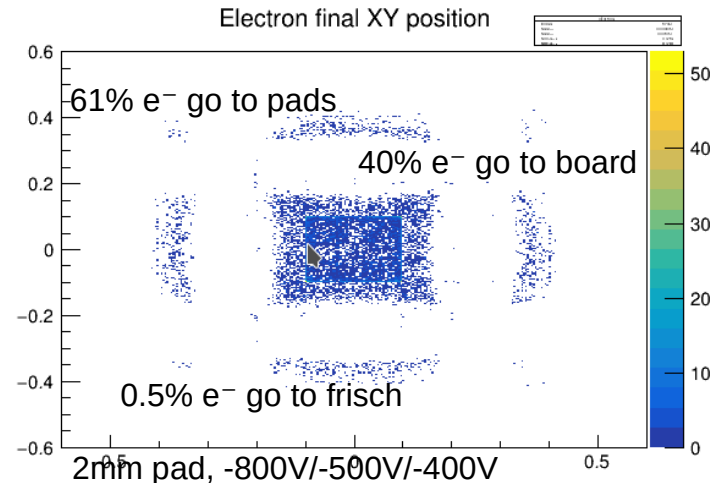
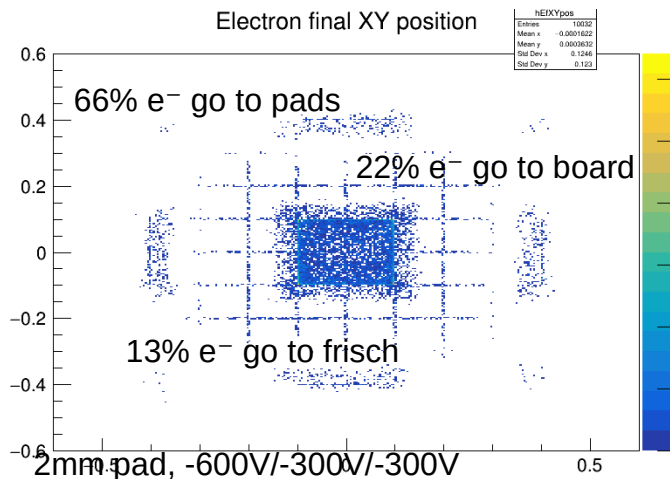
Capture of electron by the Frisch mesh

Efficiency of the guard electrodes to avoid  $e^-$  going to board insulator

Ion production at larger HV



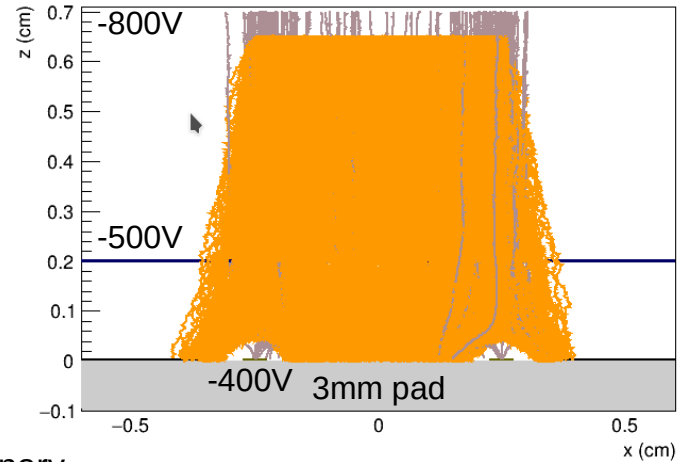
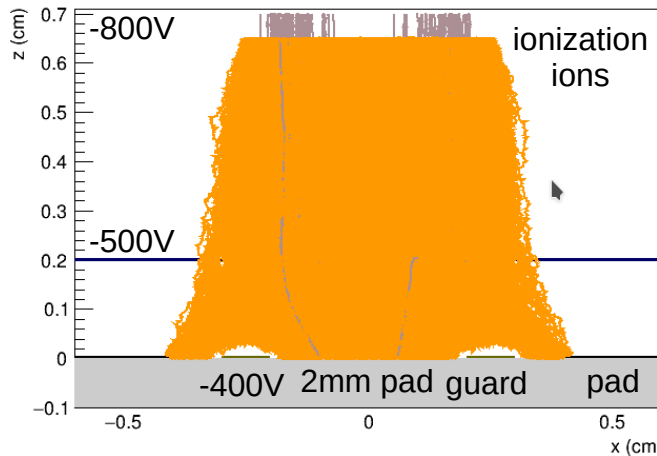
Very preliminary



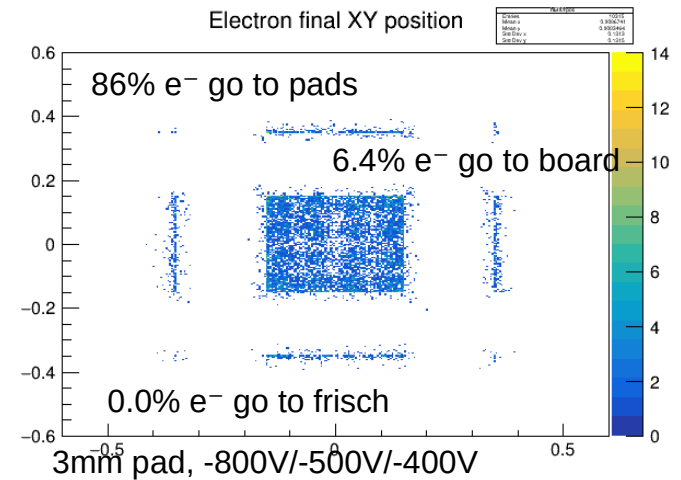
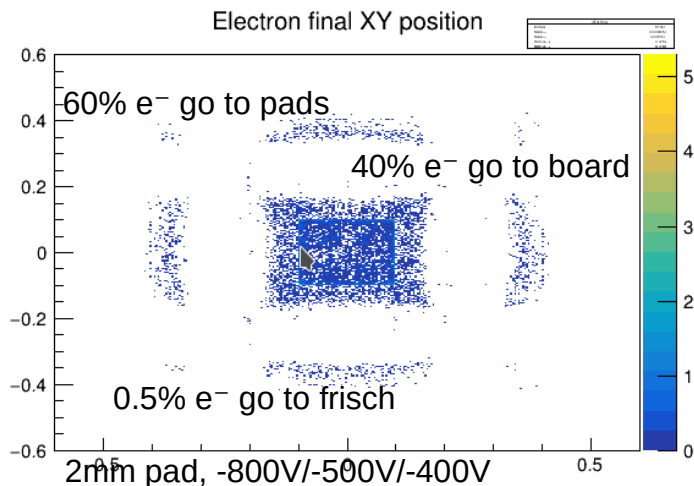
# Garfield simulation of the read-out plane

## Dependence to the read-out plane geometry

Larger pads to collect more electrons  
 But also larger capa → more noise ?



Very preliminary



# Garfield simulation: overview of performance

## Several pad sizes tested

Better electron collection with larger sizes

Not clear effects of Frisch vs guard voltages

Further studies needed

Geometry (5mm pitch)	Voltages drift/frisch/guard	% e <sup>-</sup> on pad	% e <sup>-</sup> on board	% e <sup>-</sup> on Frisch	% event with signal integral = 1	% events with 1 ion or more	% event with signal integral < 1
2mm pads 1mm guard	600/300/300	66 %	22 %	13 %	65 %	0,3 %	34 %
	800/500/400	61 %	41 %	0.4 %	57.9 %	1.3 %	40.8 %
	700/400/500	83 %	3.6 %	16 %	80 %	1.3 %	19 %
2mm pads 2mm guard	600/300/300	74 %	0.1 %	27 %	72.5 %	0.7 %	26.7 %
	800/500/400	107 %	1.6 %	4.3 %	82.1 %	9.4 %	8.4 %
	800/500/500	100 %	0 %	10.5 %	82.6 %	6.8 %	10.6 %
3mm pads 0.5mm guard	600/300/300	88 %	1.5 %	6.3 %	92 %	0.2 %	7.4 %
	800/500/400	86 %	6.4 %	0 %	91.8 %	2.5 %	5.7 %
	700/400/400	93 %	1.1 %	1.4 %	96.9 %	0.8 %	2.2 %
3.5mm pads 0.5mm guard	600/300/300	96 %	0 %	4.1 %	95.7 %	0.1 %	4.1 %
	800/500/400	100 %	0 %	0 %	98 %	1.9 %	0 %
	700/400/300	98 %	0.2 %	0.2 %	98.9 %	0.8 %	0.3 %

# Conclusion and prospects

## NoAmpTPC prototype

Most elements produced, but the whole design/production process took a very long time...

Last missing one (power/control card) under production

First tests expected end of March

## TPC simulation with Garfield++

Small 2x2mm pads probably not large enough to collect all electrons

Impact of 3x3mm (or larger) pad capacitance ?

Voltage settings to be studied with the real setup

## Prospects

Performance to be studied with the real prototype with different pad and guard strip sizes: noise level, sensitivity, efficiency, energy and spatial resolutions

Test in high pressure chamber considered

If successful larger TPC demonstrator ? Very low noise chip with integrated digitization ?